

1 **METHOD AND APPARATUS FOR FILLING VIAS**

2 **ABSTRACT OF THE INVENTION**

3 A method for filling vias, and in particular initially
4 blind vias, in a wafer, and various apparatus for
5 performing the method, comprising evacuating air from
6 the vias; trapping at least a portion of the wafer and
7 a paste for filling the vias between two surfaces; and
8 pressurizing the paste to fill the vias.